Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.042”**

**ANODE**

**.024 x .024”**

**.042”**

**CHIP BACK IS CATHODE**

**Top Material: Au**

**Backside Material: Au**

**Bond Pad Size (Anode): .024” X .024”**

**Backside Potential: Cathode**

**Mask Ref: CPD69**

**APPROVED BY: DK DIE SIZE .042” X .042” DATE: 3/8/23**

**MFG: CENTRAL SEMI THICKNESS .011” P/N: 1N4001**

**DG 10.1.2**

#### Rev B, 7/19/02